

## **Gallium Nitride 28V, 65W RF Power Transistor**

### Built using the SIGANTIC® NRF1 process - A proprietary GaN-on-Silicon technology

#### **FEATURES**

- Optimized for CW, pulsed, WiMAX, and other applications from 3300 – 3800 MHz
- 90W P<sub>3dB</sub> PEP power
- 65W P<sub>3dB</sub> CW power
- 6W linear power @ 2.0% EVM for single carrier OFDM, 10.3dB peak/avg, 3.5MHz channel bandwidth, 12dB gain, 18% efficiency
- Qualified for operation up to 32V
- 100% RF tested
- Thermally enhanced industry standard package
- High reliability gold metallization process
- · Lead-free and RoHS compliant
- Subject to 3A001b.3.a Export Control



3300 - 3800 MHz 65 Watt, 28 Volt GaN HEMT



#### RF Specifications (CW): V<sub>DS</sub> = 28V, I<sub>DQ</sub> = 750mA, Frequency = 3500MHz, T<sub>C</sub> = 25°C, Measured in Nitronex Test Fixture

Symbol	Parameter	Min	Тур	Max	Units
P <sub>3dB</sub>	Average Output Power at 3dB Compression	-	65	-	W
G <sub>SS</sub>	Small Signal Gain	11	12.5	13.5	dB
η	Drain Efficiency at 3dB Compression	40	45	-	%
Ψ	Output Mismatch Stress, VSWR = 10:1, all phase angles at 3500MHz)	No Performance Degradation After Test		er Test	

# **Typical 2-Tone Performance:** $V_{DS}$ = 28V, $I_{DQ}$ = 750mA, Frequency = 3500MHz, Tone Spacing = 0.1MHz, $T_{C}$ = 25°C Measured in Load-Pull System

Symbol	Parameter	Тур	Units
P <sub>3dB,PEP</sub>	Peak Envelope Power at 3dB Compression	93	W
P <sub>1dB,PEP</sub>	Peak Envelope Power at 1dB Compression	55	W
P <sub>IMD3</sub>	Peak Envelope Power at -35dBm IMD3	71	W

**Typical OFDM Performance:**  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, Single carrier OFDM waveform 64-QAM 3/4, 8 burst, 20ms frame, 15ms frame data, 3.5 MHz channel bandwidth. Peak/Avg. = 10.3dB @ 0.01% probability on CCDF. Frequency = 3400 - 3600MHz.  $P_{OUT,AVG}$  = 6W,  $T_{C}$  = 25°C. Measured in Nitronex Test Fixture

Symbol	Parameter	Тур	Units
G <sub>P</sub>	Power Gain	12	dB
η	Drain Efficiency	18	%
EVM	Error Vector Magnitude	2.0	%



### **DC Specifications:** T<sub>C</sub>=25°C

Symbol	Parameter	Min	Тур	Max	Units
Off Charact	eristics				
$V_{BDS}$	Drain-Source Breakdown Voltage (V <sub>GS</sub> =-8V, I <sub>DQ</sub> =36mA)	100	-	1	V
I <sub>DLK</sub>	Drain-Source Leakage Current (V <sub>GS</sub> =-8V, V <sub>DS</sub> =60V)	-	-	18	mA
On Charact	eristics				
V <sub>T</sub>	Gate Threshold Voltage (V <sub>DS</sub> = 28V, I <sub>DQ</sub> = 36mA)	-2.3	-1.8	-1.3	V
$V_{GSQ}$	Gate Quiescent Voltage (V <sub>DS</sub> = 28V, I <sub>DQ</sub> = 750mA)	-2.0	-1.5	-1.0	V
R <sub>ON</sub>	On Resistance (V <sub>GS</sub> = 2V, I <sub>DQ</sub> = 270mA)	-	0.13	0.15	Ω
I <sub>D</sub>	Drain Current ( $V_{DS}$ = 7V pulsed, 300ms pulse width, 0.2% duty cycle, $V_{GS}$ =2V)	-	19.5	1	А

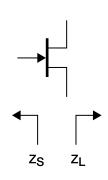
### **Absolute Maximum Ratings:** Not simultaneous, $T_C$ =25°C unless otherwise noted

Symbol	Parameter	Max	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
$V_{GS}$	Gate-Source Voltage	-10 to 3	V
P <sub>T</sub>	Total Device Power Dissipation (Derated above 25°C)	90	W
$\theta_{\sf JC}$	Thermal Resistance (Junction-to-Case)	1.95	°C/W
T <sub>STG</sub>	Storage Temperature Range	-65 to 150	°C
$T_J$	Operating Junction Temperature	200	°C
НВМ	Human Body Model ESD Rating (per JESD22-A114)	1C (>1000V)	
MM	Machine Model ESD Rating (per JESD22-A115)	M3 (>200V)	

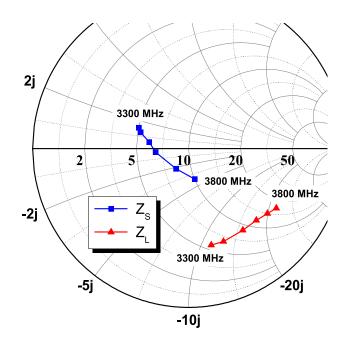


**Table 1:** Optimum Impedance Characteristics for OFDM Tuning (V<sub>DS</sub>=28V, I<sub>DQ</sub>=750 mA).

Frequency (MHz)	<b>Z</b> <sub>S</sub> (Ω)	<b>Ζ</b> L (Ω)
3300	5.0 + j1.5	5.5 - j11.0
3400	5.2 + j1.2	6.4 - j12.3
3500	6.0 + j0.5	8.9 - j14.9
3600	6.4 - j0.2	11.6 - j17.2
3700	8.2 - j2.1	14.0 - j20.1
3800	10.0 - j4.0	16.3 - j22.6



Z<sub>S</sub> is the source impedance presented to the device. Z<sub>L</sub> is the load impedance presented to the device.



**Figure 1 -** Optimal Impedances for OFDM Performance -  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA



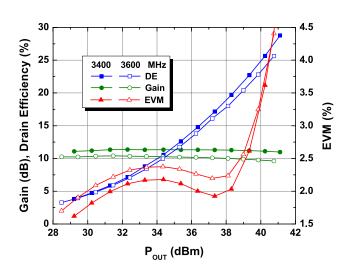


Figure 2 - Typical OFDM Performance in Nitronex Demonstration Board

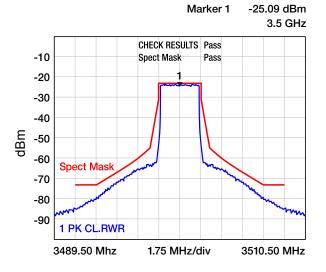
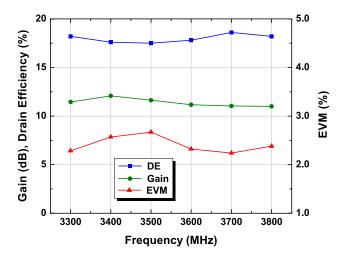
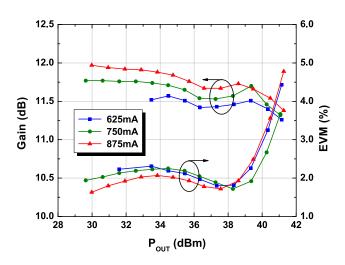


Figure 3 - ETSI Mask Compliance in Nitronex
Demonstration Board,
3500MHz and P<sub>OUT</sub> = 6W



**Figure 4 -** Typical OFDM Performance in Load-Pull System, P<sub>OUT</sub> = 6W



**Figure 5 -** Typical OFDM Performance at 3500MHz versus I<sub>DO</sub>



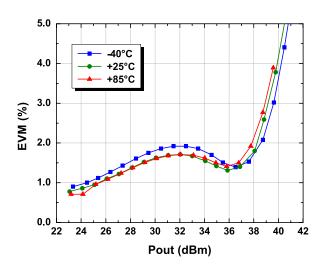


Figure 6 - Typical Device Linearity over Temperature in Nitronex Demonstration Board, V<sub>DS</sub> = 28V, I<sub>DQ</sub> = 750mA, 3400MHz

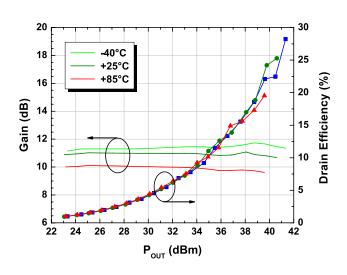


Figure 7 - Typical Device Gain and Efficiency over Temperature in Nitronex Demonstration Board,  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, 3400MHz

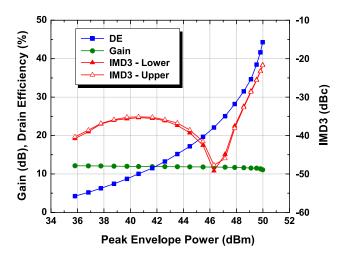
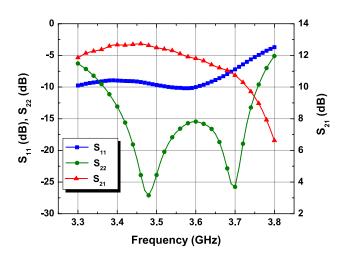
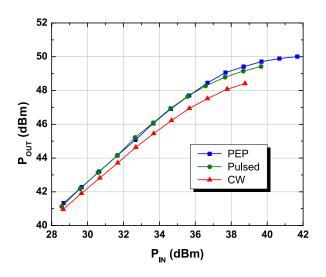


Figure 8 - Typical IMD3 Performance at  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, 3500MHa



**Figure 9 -** Typical  $S_{11}$  and  $S_{21}$  in Nitronex Demonstration Board,  $P_{IN}$  = 0 dBm,  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA





**Figure 10 -** Power Sweeps for CW, pulsed CW, and PEP,  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, 3500MHz, Constant Impedance States for All Sweeps

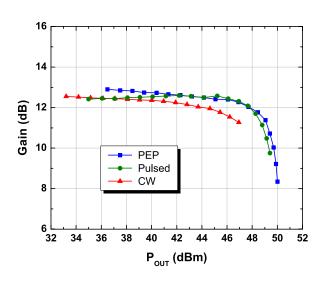


Figure 11 - Power Sweeps for CW, pulsed CW, and PEP at  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, 3500MHz, Constant Impedance States for All Sweeps

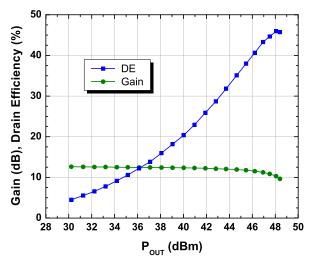


Figure 12 - CW Power Sweep,  $V_{DS}$  = 28V,  $I_{DQ}$  = 750mA, 3500MHz

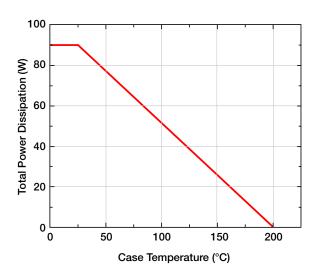


Figure 13 - Power Derating Curve



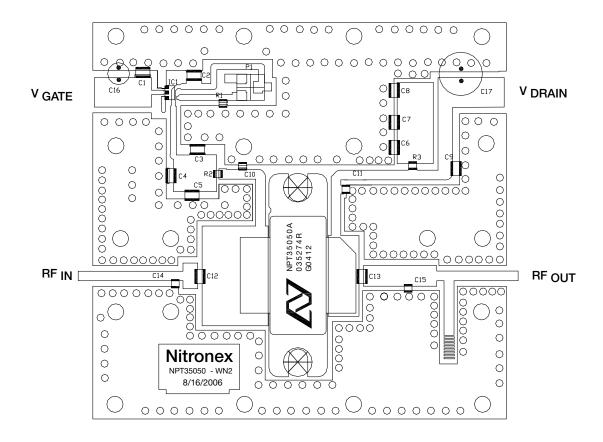


Figure 14 - APP-NPT35050A-35 Demonstration Board



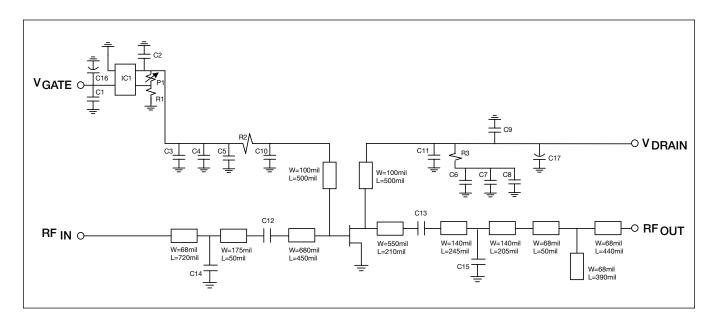


Figure 15 - APP-NPT35050A-35 Demonstration Board Equivalent Circuit

**Table 1:** APP-NPT35050A-35 Demonstration Board Bill of Materials

Component	Value	ID
C1, C2, C3	10 uF	16V Ceramic X7R (1210)
C4, C7	0.01 uF	100V Ceramic X7R (1206)
C5, C8	0.10 uF	100V Ceramic X7R (1206)
C6, C9	1.0 uF	100V CeramicX7R (1812)
C10, C11, C12, C13	5.6 pF	ATC600F5R6CT
C14	1.0 pF	ATC600F1R0AT
C15	1.5 pF	ATC600F1R5AT
C16	150uF	16V, Aluminum Electrolytic - Nichicon (PW)
C17	270uF	63V, Aluminum Electrolytic - UCC (LXY)
R1	12k ohm	0603
R2	10 ohm	0805
R3	0.33 ohm	0805
P1	20k ohm	Potentiometer - Bourns (3224 series)
IC1		IC LT1964-BYP
Substrate	Taconic RF35	t=30mil, ε <sub>r</sub> =3.5, 1 oz. Cu



#### Ordering Information<sup>1</sup>

Part Number	Description
NPT35050AB	NPT35050A in AC780B-2 Metal-Ceramic Bolt-Down Package

<sup>1:</sup> To find a Nitronex contact in your area, visit our website at http://www.nitronex.com

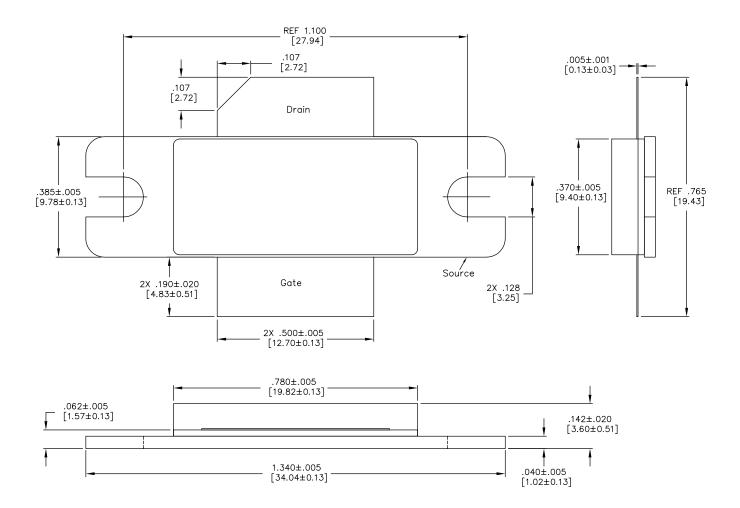


Figure 16 - AC780B-2 Metal-Ceramic Package Dimensions and Pinout (all dimensions are in inches [mm])



Nitronex, LLC

2305 Presidential Drive Durham, NC 27703 USA +1.919.807.9100 (telephone) +1.919.807.9200 (fax) info@nitronex.com www.nitronex.com

#### **Additional Information**

This part is lead-free and is compliant with the RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

#### **Important Notice**

Nitronex, LLC reserves the right to make corrections, modifications, enhancements, improvements and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to Nitronex terms and conditions of sale supplied at the time of order acknowledgment. The latest information from Nitronex can be found either by calling Nitronex at 1-919-807-9100 or visiting our website at www.nitronex.com.

Nitronex warrants performance of its packaged semiconductor or die to the specifications applicable at the time of sale in accordance with Nitronex standard warranty. Testing and other quality control techniques are used to the extent Nitronex deems necessary to support the warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

Nitronex assumes no liability for applications assistance or customer product design. Customers are responsible for their product and applications using Nitronex semiconductor products or services. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

Nitronex does not warrant or represent that any license, either express or implied, is granted under any Nitronex patent right, copyright, mask work right, or other Nitronex intellectual property right relating to any combination, machine or process in which Nitronex products or services are used.

Reproduction of information in Nitronex data sheets is permitted if and only if said reproduction does not alter any of the information and is accompanied by all associated warranties, conditions, limitations and notices. Any alteration of the contained information invalidates all warranties and Nitronex is not responsible or liable for any such statements.

Nitronex products are not intended or authorized for use in life support systems, including but not limited to surgical implants into the body or any other application intended to support or sustain life. Should Buyer purchase or use Nitronex Corporation products for any such unintended or unauthorized application, Buyer shall indemnify and hold Nitronex Corporation, its officers, employees, subsidiaries, affiliates, distributors, and its successors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, notwithstanding if such claim alleges that Nitronex was negligent regarding the design or manufacture of said products.

Nitronex and the Nitronex logo are registered trademarks of Nitronex, LLC. All other product or service names are the property of their respective owners. ©Nitronex, LLC 2012. All rights reserved.